

# BLS7G2325L-105

Power LDMOS transistor

Rev. 2 — 19 July 2011

Product data sheet

## 1. Product profile

### 1.1 General description

105 W LDMOS power transistor for S-band radar applications at frequencies from 2300 MHz to 2500 MHz.

**Table 1. Typical performance**

*Typical RF performance at  $T_{case} = 25\text{ °C}$  in a common source class-AB production test circuit.*

Mode of operation	f (MHz)	$I_{Dq}$ (mA)	$V_{DS}$ (V)	$P_{L(AV)}$ (W)	$G_p$ (dB)	$\eta_D$ (%)
Pulse CW	2300 to 2500	900	30	110	16.5	55

### 1.2 Features and benefits

- Excellent ruggedness
- High efficiency
- Low  $R_{th}$  providing excellent thermal stability
- Internally matched for ease of use
- Integrated ESD protection
- Compliant to Directive 2002/95/EC, regarding Restriction of Hazardous Substances (RoHS)

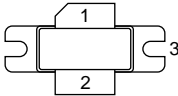
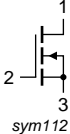
### 1.3 Applications

- RF power amplifiers for S-band radar applications in the 2300 MHz to 2500 MHz frequency range



## 2. Pinning information

**Table 2. Pinning**

Pin	Description	Simplified outline	Graphic symbol
1	drain		 sym112
2	gate		
3	source		

[1] Connected to flange.

## 3. Ordering information

**Table 3. Ordering information**

Type number	Package		
	Name	Description	Version
BLS7G2325L-105	-	flanged LDMOST ceramic package; 2 mounting holes; 2 leads	SOT502A

## 4. Limiting values

**Table 4. Limiting values**

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
$V_{DS}$	drain-source voltage		-	65	V
$V_{GS}$	gate-source voltage		-0.5	+13	V
$I_D$	drain current		-	28	A
$T_{stg}$	storage temperature		-65	+150	°C
$T_j$	junction temperature		-	200	°C

## 5. Thermal characteristics

**Table 5. Thermal characteristics**

Symbol	Parameter	Conditions	Typ	Unit
$R_{th(j-c)}$	thermal resistance from junction to case	$T_{case} = 80\text{ °C}; P_L = 100\text{ W}$	0.3	K/W

## 6. Characteristics

**Table 6. Characteristics**

$T_j = 25\text{ °C}$  unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_{(BR)DSS}$	drain-source breakdown voltage	$V_{GS} = 0\text{ V}; I_D = 1\text{ mA}$	65	-	-	V
$V_{GS(th)}$	gate-source threshold voltage	$V_{DS} = 10\text{ V}; I_D = 150\text{ mA}$	1.5	1.8	2.3	V
$I_{DSS}$	drain leakage current	$V_{GS} = 0\text{ V}; V_{DS} = 28\text{ V}$	-	-	5	$\mu\text{A}$
$I_{DSX}$	drain cut-off current	$V_{GS} = V_{GS(th)} + 3.75\text{ V}; V_{DS} = 10\text{ V}$	25.1	29	-	A
$I_{GSS}$	gate leakage current	$V_{GS} = 11\text{ V}; V_{DS} = 0\text{ V}$	-	-	500	nA
$g_{fs}$	forward transconductance	$V_{DS} = 10\text{ V}; I_D = 5.35\text{ A}$	-	10.5	-	S
$R_{DS(on)}$	drain-source on-state resistance	$V_{GS} = V_{GS(th)} + 3.75\text{ V}; I_D = 5.25\text{ A}$	-	0.1	-	$\Omega$

## 7. Test information

**Remark:** All testing performed in a class-AB production test circuit.

**Table 7. Functional test information**

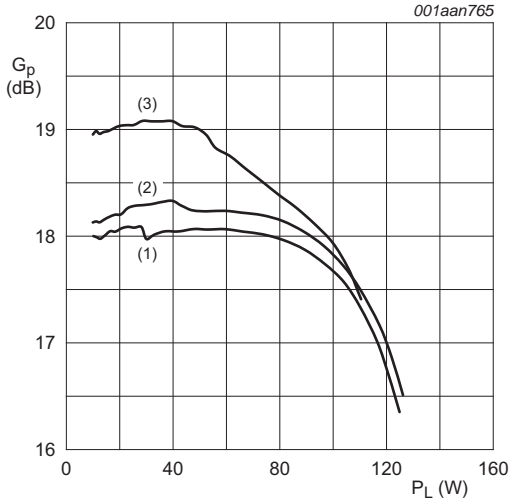
Mode of operation: 1-carrier N-CDMA, single carrier IS-95 with pilot, paging, sync and 6 traffic channels (Walsh codes 8 - 13). PAR = 9.7 dB at 0.01 % probability on the CCDF, channel bandwidth is 1.2288 MHz;  $f_1 = 2300\text{ MHz}; f_2 = 2500\text{ MHz};$  RF performance at  $V_{DS} = 28\text{ V}; I_{Dq} = 900\text{ mA}; T_{case} = 25\text{ °C};$  unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$P_{L(AV)}$	average output power		-	20	-	W
$G_p$	power gain		17.3	18	-	dB
$RL_{in}$	input return loss		-	-10	-	dB
$\eta_D$	drain efficiency		22	27	-	%
$ACPR_{885k}$	adjacent channel power ratio (885 kHz)		-	-46	-40	dBc

### 7.1 Ruggedness in class-AB operation

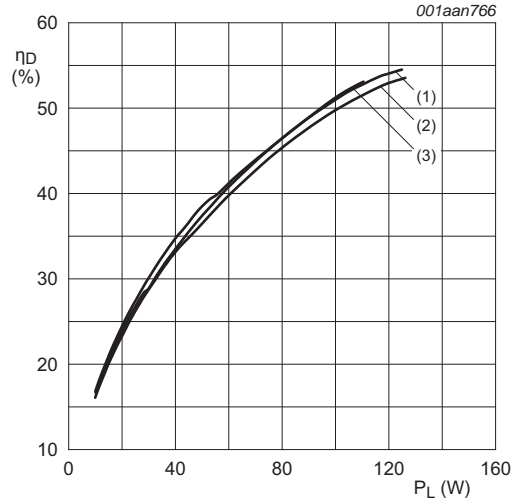
The BLS7G2325L-105 is capable of withstanding a load mismatch corresponding to  $VSWR = 10 : 1$  through all phases under the following conditions:  $V_{DS} = 28\text{ V}; I_{Dq} = 900\text{ mA}; P_L = 100\text{ W (CW)}; f = 2300\text{ MHz}.$

**7.2 Pulsed CW**



$V_{DS} = 28\text{ V}; I_{Dq} = 900\text{ mA}.$   
 (1)  $f = 2300\text{ MHz}$   
 (2)  $f = 2400\text{ MHz}$   
 (3)  $f = 2500\text{ MHz}$

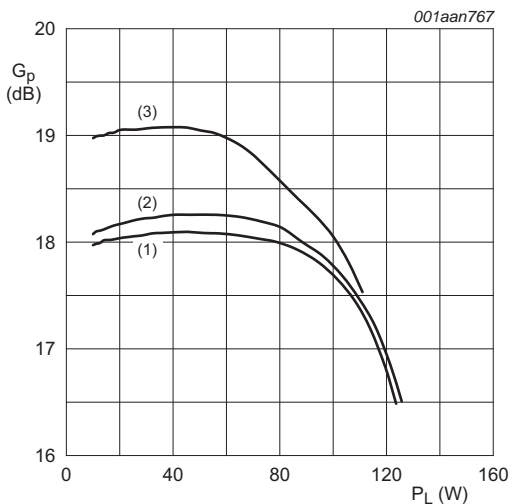
**Fig 1. Pulsed CW power gain as a function of load power; typical values**



$V_{DS} = 28\text{ V}; I_{Dq} = 900\text{ mA}.$   
 (1)  $f = 2300\text{ MHz}$   
 (2)  $f = 2400\text{ MHz}$   
 (3)  $f = 2500\text{ MHz}$

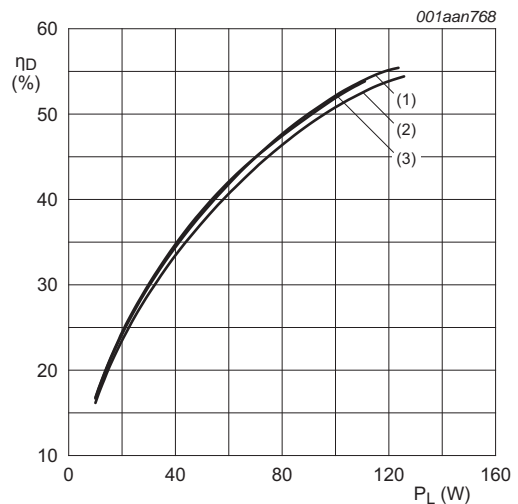
**Fig 2. Pulsed CW drain efficiency as a function of load power; typical values**

**7.3 CW**



$V_{DS} = 28\text{ V}; I_{Dq} = 900\text{ mA}.$   
 (1)  $f = 2300\text{ MHz}$   
 (2)  $f = 2400\text{ MHz}$   
 (3)  $f = 2500\text{ MHz}$

**Fig 3. CW power gain as a function of load power; typical values**



$V_{DS} = 28\text{ V}; I_{Dq} = 900\text{ mA}.$   
 (1)  $f = 2300\text{ MHz}$   
 (2)  $f = 2400\text{ MHz}$   
 (3)  $f = 2500\text{ MHz}$

**Fig 4. CW drain efficiency as a function of load power; typical values**

**8. Package outline**

Flanged LDMOST ceramic package; 2 mounting holes; 2 leads

SOT502A

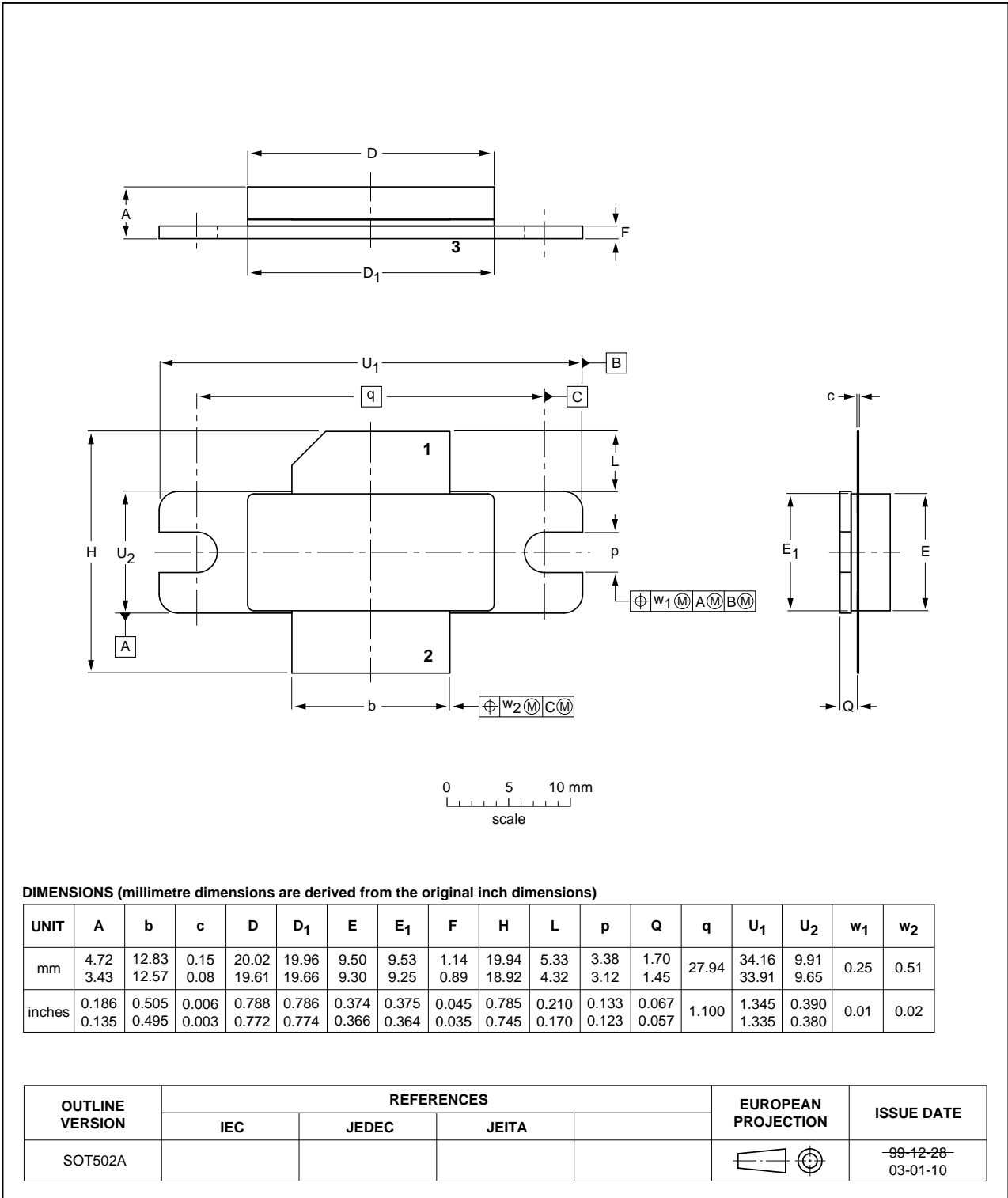


Fig 5. Package outline SOT502A

## 9. Abbreviations

**Table 8. Abbreviations**

Acronym	Description
CCDF	Complementary Cumulative Distribution Function
CW	Continuous Wave
IS-95	Interim Standard 95
ESD	ElectroStatic Discharge
LDMOS	Laterally Diffused Metal Oxide Semiconductor
LDMOST	Laterally Diffused Metal Oxide Semiconductor Transistor
N-CDMA	Narrowband Code Division Multiple Access
PAR	Peak-to-Average power Ratio
RF	Radio Frequency
S-band	Short wave Band
VSWR	Voltage Standing Wave Ratio

## 10. Revision history

**Table 9. Revision history**

Document ID	Release date	Data sheet status	Change notice	Supersedes
BLS7G2325L-105 v.2	20110719	Product data sheet	-	BLS7G2325L-105 v.1
Modifications:	<ul style="list-style-type: none"> <li>The status of this document has been changed to Product data sheet.</li> </ul>			
BLS7G2325L-105 v.1	20110301	Objective data sheet	-	-

## 11. Legal information

### 11.1 Data sheet status

Document status <sup>[1][2]</sup>	Product status <sup>[3]</sup>	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

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[2] The term 'short data sheet' is explained in section "Definitions".

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